

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A method of fabricating a semiconductor device comprising:
  - (a) attaching a plurality of semiconductor chips to a tape;
  - (b) cutting the tape to obtain substrates after the step (a); and
  - (c) providing a plurality of external terminals on each of the substrates after the step (b),wherein the steps (a) and (b) are carried out in a reel-to-reel transport system.
2. (Previously Amended) The method of fabricating a semiconductor device as defined in claim 1, further comprising:

attaching a reinforcing member to the tape in positions corresponding to each of the semiconductor chips, before the step (b).
3. (Original) The method of fabricating a semiconductor device as defined in claim 1,

wherein the tape is cut into regions each including one of the semiconductor chips in the step (b).
4. (Original) The method of fabricating a semiconductor device as defined in claim 2,

wherein the tape is cut into regions each including one of the semiconductor chips in the step (b).
5. (Original) The method of fabricating a semiconductor device as defined in claim 1,

wherein the tape is cut into regions each including two or more of the semiconductor chips in the step (b).

6. (Original) The method of fabricating a semiconductor device as defined in claim 2,

wherein the tape is cut into regions each including two or more of the semiconductor chips in the step (b).

7. (Currently Amended) The method of fabricating a semiconductor device as defined in claim 5, further comprising:

cutting each of the substrates into regions, each including one of the semiconductor chips, after the step (c).

8. (Currently Amended) The method of fabricating a semiconductor device as defined in claim 6, further comprising:

cutting each of the substrates into regions, each including one of the semiconductor chips, after the step (c).

9. (Previously Amended) The method of fabricating a semiconductor device as defined in claim 1,

wherein a plurality of device holes are formed in the tape, and leads are formed on the tape, which end portions project into the respective device holes; and

wherein each of the semiconductor chips is disposed within a respective one of the device holes, and the electrodes of the semiconductor chips and the leads are bonded in the step (a).

10. (Withdrawn)

11. (Withdrawn)

12. (Original) The method of fabricating a semiconductor device as defined in claim 1,

wherein each of the semiconductor chips is bonded to the tape in a face-up configuration in the step (a).

13. (Previously Amended) The method of fabricating a semiconductor device as defined in claim 12,

wherein the electrodes of the semiconductor chips and leads formed on the tape are electrically connected by means of wires in the step (a).

14. (Previously Amended) The method of fabricating a semiconductor device as defined in claim 1, further comprising:

attaching a heat radiating member to each of the semiconductor chips.

15. (Previously Amended) The method of fabricating a semiconductor device as defined in claim 2, further comprising:

attaching a heat radiating member to each of the semiconductor chips.

16. (Previously Amended) The method of fabricating a semiconductor device as defined in claim 1, further comprising:

attaching the heat radiating member before the step (b), with a reel-to-reel transport system.

17. (Previously Amended) The method of fabricating a semiconductor device as defined in claim 2, further comprising:

attaching the heat radiating member before the step (b), with a reel-to-reel transport system.

18. (Original) A semiconductor device fabricated by the method as defined in claim 1.

19. (Original) A circuit board having mounted the semiconductor device as defined in claim 18.

20. (Original) An electronic apparatus including the semiconductor device as defined in claim 18.